



# RC7310 High Speed Driver

#### **Features**

- High output slew rate (1.2 V/ns minimum)
- Wide output voltage range (-3.0V to +8V), and up to 10 Vp-p swings
- 250 MHz minimum operation for ECL swings
- Wide input common mode range for ease of interface to ECL as well as TTL and CMOS
- Output short-circuit protection with current limiter and thermal shutdown
- 100 mA dynamic switching current drive
- · Absolute slew rate control
- Low output voltage offset (30 mV typ.) and output offset drift (0.1 mV/°C typ.)
- Low input bias current (1 μA typ.) and current drift (40 nA/°C typ.) for output level program voltage allows direct coupling to a DAC output
- Available in 28-pin PLCC

# **Applications**

- · Differential line driver/receiver
- Precision waveform generator
- · Level translator
- Switch driver
- Laser driver
- CRT preamplifier

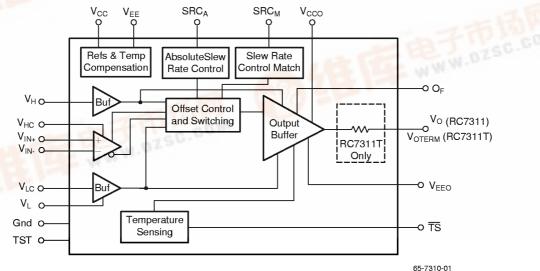
### Description

The RC7310 is a low cost High Speed Driver capable of over 250 MHz operation at ECL levels and greater than 1.2 V/ns slew rate for 5 Vp-p output. The driver offers programmable output levels between -3.0V and +8V and an output amplitude up to 10 Vp-p. It is therefore capable of driving any logic family such as ECL, TTL and CMOS. The high and low limits of the output swing are set through the program pins VH and VL, respectively. The transfer characteristic from the program pins to the output pin is unity gain with low offset (30 mV typical) and offset drift (0.1 mV/°C typical). The VH and VL inputs have been buffered to operate with low bias currents (1.0  $\mu A$  typical) allowing direct coupling to the output of a DAC.

The RC7310 is normally driven by ECL levels. However, the input common mode range, -2V to +6V, is wide enough to accommodate TTL or CMOS input signals. When driven with a single ended signal the other input of the RC7310 must be tied to the appropriate threshold voltage.

The RC7310 is specified at nominal power supply values of 10V and -5.2V, and commensurate output voltage swing limits of -3.0V and +8V.

# **Block Diagram**





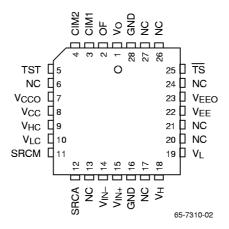
# **Description (continued)**

The supply rails may be raised by 2V to achieve an output high level (VOH) of +1 0V, or towered by 2V to achieve an output low level (VOL) of -5V. At all times there must be at least a 2V margin between the positive supply and the maxi-

mum value of  $V_{OH}$ , and between the negative supply and the minimum value of  $V_{OL}$ .

The RC7310 is implemented using Fairchild Semiconductor's high performance precision Complementary Bipolar Process (CBiP).

## **Pin Assignments**



## **Pin Definitions**

Pin Name	Pin Number	Pin Function Description
CIM1, CIM2	3, 4	An optional 10,000 pF chip capacitor could be placed between CIM1 and CIM2 to improve impedance matching across different voltage swings. With this capacitor, output impedance stays more constant with changes in voltage swings. If not used, leave pins CIM1 and CIM2 open.
GND	16, 28	Chip ground. These pins should be connected to the printed circuit board's ground plane at the pins.
OF	2	On chip filter to improve output waveform (optional). This pin connection is optional and should be left unconnected if not used. When used, the OF pin should be fed to the termination node that is directly connected to the DUT.
SRCA	12	Absolute slew rate control. By applying current at this pin, small changes in slew rate can be programmed with an external DAC. This control pin affects both positive and negative edge rates. If this slew rate control is not desired this pin should be left open.
SRCM	11	Slew rate control matching. By applying current at this pin, small changes in slew rate can be programmed with an external DAC. This control pin adjusts the match between positive and negative edges. If this slew rate control is not desired this pin should be left open.
TS	25	Active low output notifies thermal shutdown has occurred. In the event of a short-circuit or other fault that causes the die temperature to rise between 115°C and 160°C, the thermal shutdown will activate. If the fault persists, the device will toggle back and forth between shutdown and normal operation at a frequency in the tens of Hertz. TS is an open collector output capable of driving two standard TTL loads. The TS pins of several drivers may be wired together and input to a latch to indicate an alarm condition.
TST	5	Pin used for factory testing the thermal characteristics of the device. The pin should be left unconnected or tied to GND.

# Pin Definitions (continued)

Pin Name	Pin Number	Pin Function Description
Vcc	8	Quiet positive supply. The nominal value is 10V ±3%. For output high voltage levels (VOH) greater than the nominal value of +8V, VCC should be raised 2V above the maximum VOH value. Whenever VEE is lowered to provide margin at the output low level, VCC should also be lowered by the same amount. VCC should be bypassed to the ground plane with a 10,000 pF chip capacitor placed as close to the pin as possible.
Vcco	7	Positive supply for the output stage. This supply is brought out separately to minimize the supply noise generated when the output switches. VCCO should be bypassed to the ground plane with a 10,000 pF chip capacitor placed as close to the pin as possible and then immediately connected to VCC.
VEE	22	Quiet negative supply. The nominal value is -5.2V to ±5%. For output low voltage levels (VoL) less than 3V, VEE should be lowered 2V below the minimum VoL value. Whenever VcC is raised to provide margin at the output high level, VEE should be raised by the same amount. VEE should be bypassed to ground with a 10,000 pF chip capacitor placed as close to the pins as possible.
VEEO	23	Negative supply for the output stage. This supply is brought out separately to minimize the supply noise generated when the output switches. VEEO should be bypassed to the ground plane with a 10,000 pF chip capacitor placed as close to the pin as possible and then immediately connected to VEE.
VH	18	Analog program input that sets the output high level (VOH). The transfer characteristic from VH to VOH is nominally unity gain.
VHC	9	Bypass for analog program input high, V <sub>H</sub> . V <sub>HC</sub> should be bypassed to the ground plane with a 1000 pF chip capacitor placed as close to the pin as possible.
VIN+, VIN-	15, 14	Differential digital inputs. The output will toggle between the two levels dictated by VH and VL as the differential signal is switched. Although these inputs will normally be driven by ECL signals, they have a wide enough common mode range that any one of the inputs may be driven by a TTL or CMOS signal provided that the other input is tied to the appropriate threshold voltage.
VL	19	Analog program input that sets the output low level ( $V_{OL}$ ). The transfer characteristic from $V_L$ to $V_{OL}$ is nominally unity gain.
VLC	10	Bypass for analog program input low, V <sub>L</sub> . V <sub>L</sub> C should be bypassed to the ground plane with a 1000 pF chip capacitor placed as close to the pin as possible.
Vo	1	Driver output of RC7310. The output impedance is $12.6\Omega \pm 1.5\Omega$ . The output is usually back terminated in the characteristic impedance of the driven transmission line. For a $50\Omega$ line, a $37.4\Omega \pm 1\%$ or better resistor should be placed externally as close to the output pin as possible to minimize reflections and ringing. The resistor should also be able to dissipate $0.8\Omega$ to sustain the short circuit current of the output.
NC	6, 13, 17, 20, 21, 24, 26, 27	No connection.

# Absolute Maximum Ratings<sup>1</sup>

Parameter	Min.	Max.	Unit	
Positive power supply, VCC		13	V	
Negative power supply, VEE			-8.2	V
Difference between VCC and VEE			16	V
Input voltage at V <sub>IN+</sub> , V <sub>IN-</sub> V <sub>CC</sub>		-12		V
	VEE		+12	1
Input voltage at V <sub>H</sub> , V <sub>L</sub>	Vcc	-13		V
	VEE		+13	1
Differential input voltage, IV <sub>IN+</sub> – V <sub>IN-</sub> I		6	V	
Difference between $V_H$ and $V_L$ , $(IV_H-V_L$	l)		13	V
Driver output voltage	Vcc	-13		V
	VEE		+13	1
Output voltage at TS		7	V	
Duration of short-circuit to ground	Indefinite			
Operating temperature range	0	70	°C	
Storage temperature range	-65	+125	°C	
Lead temperature range (soldering 10 sec	conds)		300	°C

Absolute Maximum Ratings are those beyond which the safety of the device cannot be guaranteed. They are not meant to
imply that the device should be operated at these limits. If the device is subjected to the limits in the absolute maximum ratings
for extended periods, its reliability may be impaired. The tables of Electrical Characteristics provide conditions for actual
device operation.

# **Operating Conditions**

Symbol	Parameter	Min.	Тур.	Max.	Unit
TC	Case operating temperature <sup>1</sup>	0		70	°C
Vcc	Positive supply voltage	9.7	10.0	10.3	V
VEE	Negative supply voltage	-5.45	-5.2	-4.95	٧
VCC - VEE	Difference between positive and negative supply		15.2	15.8	٧
Voh, Vol	Range for output high level and output low level	VEE+2		Vcc-2	٧
IV <sub>OH</sub> – V <sub>OL</sub> I	Output amplitude	0.4		10.0	٧
RT	Output back-termination resistor for RC7310		37.4		Ω

#### Note:

# **DC Electrical Characteristics**

VCC = 10V ±3%, VEE = -5.2V ±5%, TA = 25°C (still air), no load, unless otherwise specified.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Differentia	I Inputs, V <sub>IN+</sub> , V <sub>IN</sub> _	•				
VIN+, VIN-	Absolute Input Voltage		-2.0		+6.0	٧
VID	Differential Input Range	IV <sub>IN+</sub> – V <sub>IN</sub> –I	0.4	ECL	5.0	V
I <sub>IN+</sub> , I <sub>IN</sub> _	Bias Current	-2V ≤ V <sub>IN±</sub> ≤ +6V		-100	-250	μΑ
Absolute S	SLR Control, SRCA	•				
Vsrca	Compliance Voltage Range	VH = +5V, VL= 0V	-2.3	-1.6	-0.9	V
ISRCA	Control Current Range		-1.0		+1.0	mA
%SLRMax	%SLR Absolute Change	V <sub>com</sub> = -2.0		-20		%
%SLRMax	%SLR Absolute Change	Vcom = -2.4		-40/+25		%
Matching S	SLR Control, SRCM			•		
Vsrcm	Compliance Voltage Range	VH = +5V, VL= 0V	0.4	0.6	0.9	V
ISRCM	Control Current Range		-0.5		+0.5	mA
%SLR	Max % SLR Matching Change			30		%
Voltage Pro	ogram Inputs V <sub>H</sub> , V <sub>L</sub>			•		
VH	V <sub>H</sub> Range	VCC = 10V, VEE = -5.2V	-1.0		+8.0	V
		VCC = 12V, VEE = -3.2V	+1.0		+10.0	V
		VCC = 8V, VEE = -7.2V	-3.0		+6.0	V
VL	V <sub>L</sub> Range	VCC = 10V, VEE = -5.2V	-3.0		+5.5	V
		VCC = 12V, VEE = -3.2V	-1.0		+7.5	٧
		VCC = 8V, VEE = -7.2V	-5.0		+3.5	V
VA	IV <sub>OH</sub> – V <sub>OL</sub> I	Output Voltage Amplitude	0.40		10	V
lн	Bias Current @ V <sub>H</sub>	-1.0V ≤ V <sub>H</sub> ≤ +8V; V <sub>L</sub> = -3.0V		-1.0	-5.0	μΑ
IL	Bias Current @ VL	-3V ≤ V <sub>L</sub> ≤ +5.5V; V <sub>H</sub> +8.0V		-1.0	-5.0	μΑ
TCIH	Max. Temperature Drift in IH	V <sub>H</sub> = 7.0V; 25°C ≤ T <sub>A</sub> ≤ 70°C; (output not switching)			40	nA/°C
TCIL	Max. Temperature Drift in IL	VL = -2.0V; 25°C ≤ TC ≤ 70°C; (output not switching)			40	nA/°C

<sup>1.</sup> With air flow >300 lfpm.

# DC Electrical Characteristics (continued)

VCC = 10V ±3%, VEE = -5.2V ±5%, TA = 25°C (still air), no load, unless otherwise specified.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
ΔIBDC	Variation in IH, IL with Power Supply and DC Voltage at VH or VL	V <sub>H</sub> = -1.0V to +8V; V <sub>L</sub> = -3V to +5.5V	-2.0		+2.0	μΑ
V <sub>H</sub> ,LBW	VH,L BW	-3 dB point from V <sub>H,L</sub> BW to V <sub>OUT</sub>		50		kHz
Signal Ou	tput Vo, Voterm	•				
Vон	Range for High Level Voltage	VCC = 10V, VEE = -5.2V	-1.0		+8.0	V
		VCC = 12V, VEE = -3.2V	+1.0		+10.0	V
		VCC = 8V, VEE = -7.2V	-3.0		+6.0	V
VoL	Range for Low Level Voltage	VCC = 10V, VEE = -5.2V	-3.0		+5.5	V
		VCC = 12V, VEE = -3.2V	+1.0		+7.5	V
		VCC = 8V, VEE = -7.2V	-5.0		+3.5	V
δVон	Offset to Output High Level	$\delta V_{OH} =  V_H - V_{OH} , V_H = 0V, V_L = -3V, -1.0V \le V_H \le +8V, V_L = -2V$		30	100	mV
δVOL	Offset to Output Low Level	$\delta V_{OL} = I_{VL} - V_{OL}I, V_{H} = 8V, V_{L} = 0V, -3V \le V_{L} \le +5.5V, V_{L} = +7V$		30	100	mV
VTC	Output Voltage Drift	-3V ≤ V <sub>L</sub> ≤ +5.5V, -1.0V ≤ V <sub>H</sub> ≤ +8V		0.1	0.5	mV/°C
εG	Gain Error	-3.0V ≤ V <sub>L</sub> ≤ +5.5V, V <sub>H</sub> = +8V, -1.0V ≤ V <sub>H</sub> ≤ +7.5V, V <sub>L</sub> = -3V	-1.0		+1.0	%VSET
εL	Linearity Error	0V ≤ V <sub>L</sub> ≤ +5V, V <sub>H</sub> = +8V, 0V ≤ V <sub>H</sub> ≤ +5V, V <sub>L</sub> = -3V	-0.3		+0.3	%VSET
		$-3.0V \le V_L \le +5.5V$ , $V_H = +8V$ , $-1.0V \le V_H \le +7.5V$ , $V_L = -3V$	-0.5		+0.5	%VSET
Zout	Output Impedance	Vo (RC7310)		12.6		Ω
IAC	AC Current Drive		70	100		m <b>A</b>
IDC	DC Current Drive		50			m <b>A</b>
Thermal S	Shutdown Output (TS)					
VoL	Output Low Level	IOL = 4 mA			0.5	V
ICL	DC Current Limit		70	110	130	mA
TS	Shutdown Die Temperature		115	130	160	°C
Other						
Icc	Positive Supply Current			60		mA
IEE	Negative Supply Current			60		mA
PSRVo	Output Level to Power Supply Rejection Ratio	V <sub>CC</sub> ; ΔV <sub>CC</sub> = ±2.5% V <sub>EE</sub> ; ΔV <sub>EE</sub> = ±2.5%	40 40			dB dB
PSRV <sub>SL</sub>	Output Slew Rate to Power Supply Rejection Ratio	VCC; $\Delta$ VCC = $\pm 200$ mV VEE; $\Delta$ VEE = $\pm 200$ mV			4 4	% %
Тд	Operating Temperature Range	Still Air	0	25	50	°C
		Air Flow > 300 Ifpm	0	25	70	°C

#### **AC Electrical Characteristics**

 $V_{CC} = 10V \pm 3\%$ ,  $V_{EE} = -5.2V \pm 5\%$ ,  $T_{A} = 25^{\circ}C$  (still air) and the load is a  $50\Omega$  transmission line with 2.0 ns one-way delay, unless otherwise specified. The transmission line should be back-terminated in  $50\Omega$  ( $\pm 1\%$ ) using an external resistor. The measurement probe is a high impedance FET probe with capacitance no greater than 6 pF and resistance no smaller than  $10 \text{ k}\Omega$ .

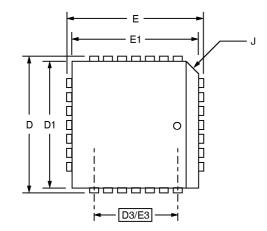
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit		
SLR	Slew Rate VH – VL = 5V; measured between 20% and 80% points							
	(SRCM and SRCA	With probe only as load	1.2	1.6		V/ns		
	Adjusted)	With probe and transmission line	1.1	1.5		V/ns		
SLR	Slew Rate	V <sub>H</sub> – V <sub>L</sub> = 5V; measured between 20% and 80% points						
	(No SRCM and SRCA	With probe only as load	1.0	1.4		V/ns		
	Adjustment)	With probe and transmission line	1.0	1.4		V/ns		
tR, tF	Rise Time and Fall Time	Load is Probe Only				•		
	(SRCM and SRCA	Amplitude = 0.8V (20% to 80%)		0.6	0.8	ns		
	Adjusted)	3V (10% to 90%)		1.7	2.0	ns		
		5V (10% to 90%)		2.4	2.9	ns		
		9V (10% to 90%)		4.0	4.8	ns		
tR, tF	Rise Time and Fall Time	Load is Probe Only						
	(No SRCM and SRCA	Amplitude = 0.8V (20% to 80%)		0.7	1.0	ns		
	Adjustment)	3V (10% to 90%)		2.0	2.4	ns		
		5V (10% to 90%)		2.8	3.6	ns		
		9V (10% to 90%)		4.8		ns		
f	Toggle Rate	Amplitude = 0.8V	250	270		MHz		
		Amplitude = 5.0V	105	110		MHz		
Propagat	ion Delay							
tPLH	Low to High	f = 10 MHz; V <sub>OH</sub> = +0.4V;		1.6	2.0	ns		
tPHL	High to Low	V <sub>OL</sub> = -0.4V		1.6	2.0	ns		
Δtp	Matching ItPLH - tPHLI			150	175	ps		
ΔtpTC	Temperature Coefficient			2		ps/°C		
tPWMIN	Minimum Pulse Width	VH – VL = 2.0V; Pulse Width at which amplitude drops by 50mV, measured between 50% points	2.0			ns		
∆tpPW	Propagation Delay Variation with Pulse Width	2ns < PW < 98ns; f = 10 MHz; V <sub>OH</sub> = +0.4V; V <sub>OL</sub> = -0.4V	-75		+75	ps		
PS	Preshoot	0.5V < IV <sub>OH</sub> – V <sub>OL</sub> I < 5V		15 mV + 3% of VA		mV		
OS	Overshoot	0.5V < IV <sub>OH</sub> – V <sub>OL</sub> I < 5V		50 mV + 4% of VA		mV		
ts	Output Setting Time	IVOH – VOLI = 5V	•			-		
		To within 3% of IVOH - VOLI		5		ns		
		To within 1% of IVOH – VOLI		10		ns		

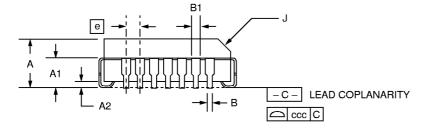
## **Mechanical Dimensions**

#### 28-Lead PLCC

Cumbal	Inches		Millin	Notes	
Symbol	Min.	Max.	Min.	Max.	Notes
Α	.165	.180	4.19	4.57	
A1	.090	.120	2.29	3.05	
A2	.020		.51	_	
В	.013	.021	.33	.53	
B1	.026	.032	.66	.81	
D/E	.485	.495	12.32	12.57	
D1/E1	.450	.456	11.43	11.58	3
D3/E3	.300 BSC		7.62	BSC	
е	.050	BSC	1.27	BSC	
J	.042	.048	1.07	1.22	2
ND/NE	7		7		
N	2	8	28		·
ccc		.004	_	0.10	

- 1. All dimensions and tolerances conform to ANSI Y14.5M-1982
- 2. Corner and edge chamfer (J) = 45°
- 3. Dimension D1 and E1 do not include mold protrusion. Allowable protrusion is .101" (.25mm)





## **Ordering Information**

Part Number	Package	Operating Temperature Range
RC7310QA	28-Pin PLCC	0°C to +70°C

#### LIFE SUPPORT POLICY

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- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.